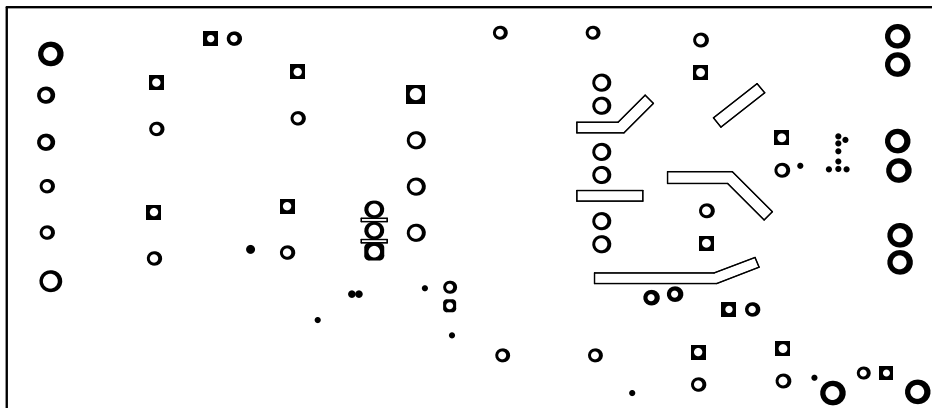
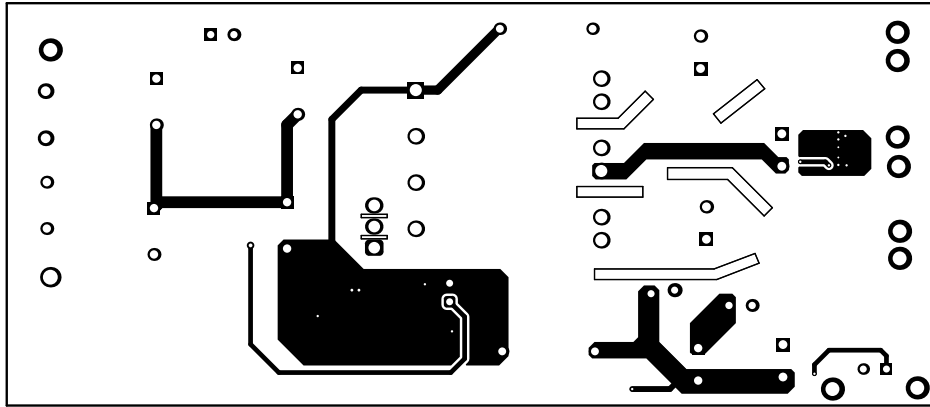


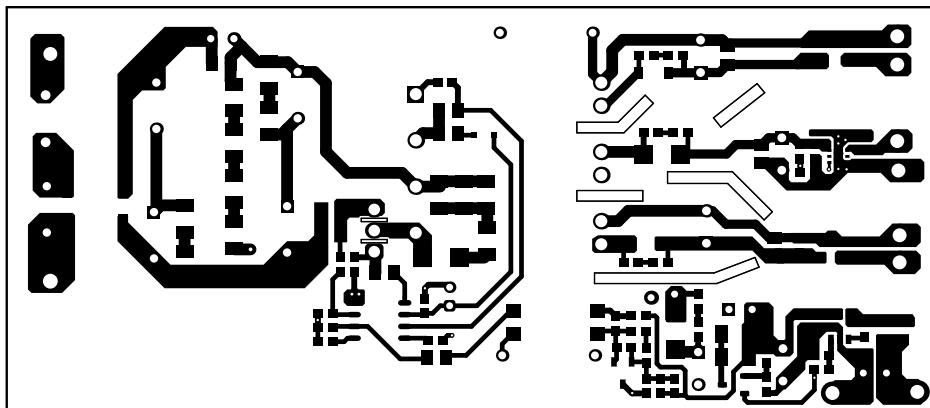
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40381		
PLOT NAME = Top Overlay	GENERATED : 4/3/2018	5:31:46 PM	TEXAS INSTRUMENTS



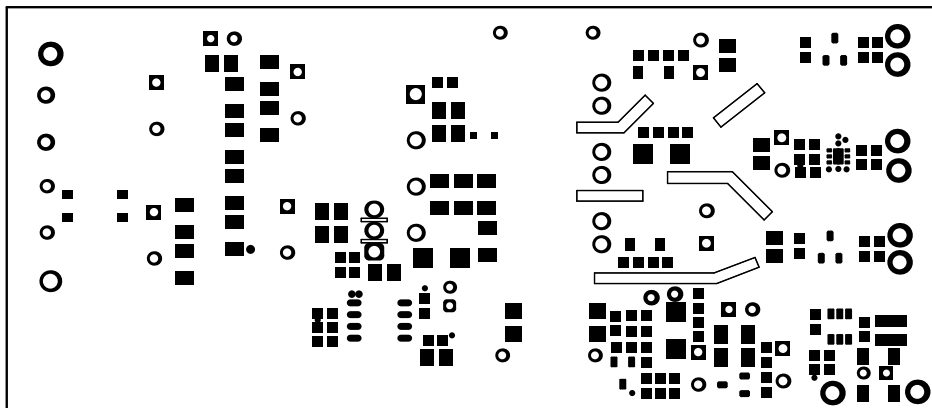
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40381		
PLOT NAME = Top Solder Mask	GENERATED : 4/3/2018 5:31:47 PM	TEXAS INSTRUMENTS	



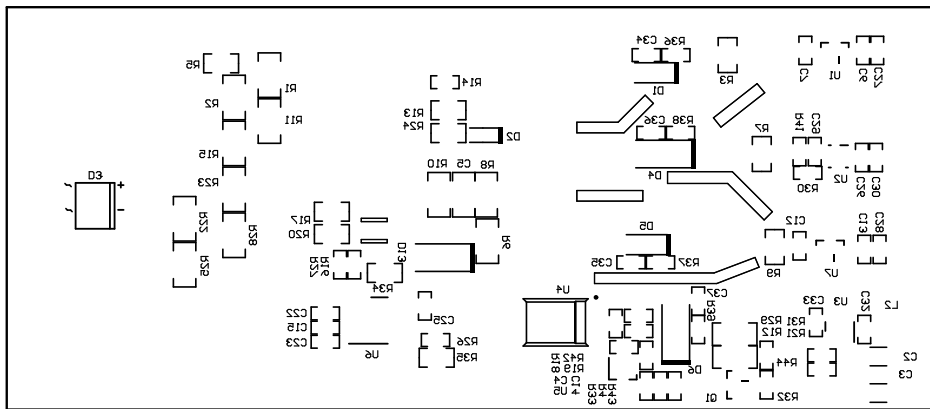
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40381		
PLOT NAME = Top Layer	GENERATED : 4/3/2018 5:31:47 PM	TEXAS INSTRUMENTS	



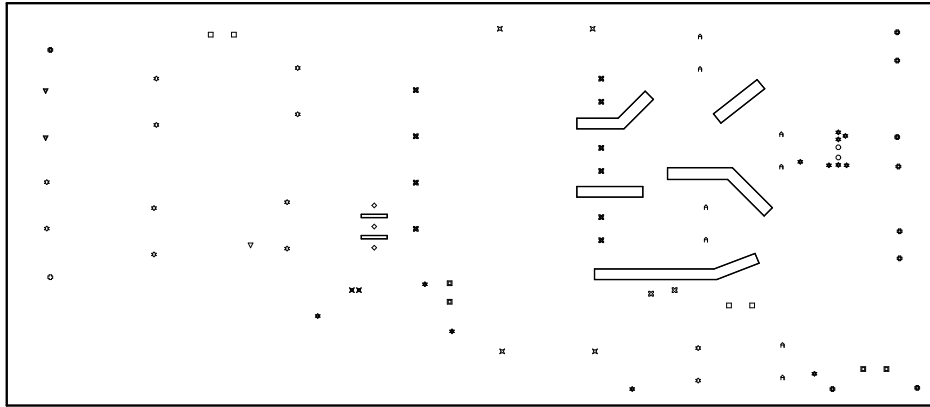
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40381		
PLOT NAME = Bottom Layer	GENERATED : 4/3/2018 5:31:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40381		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/3/2018 5:31:47 PM	TEXAS INSTRUMENTS	

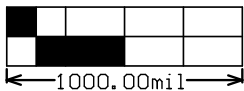
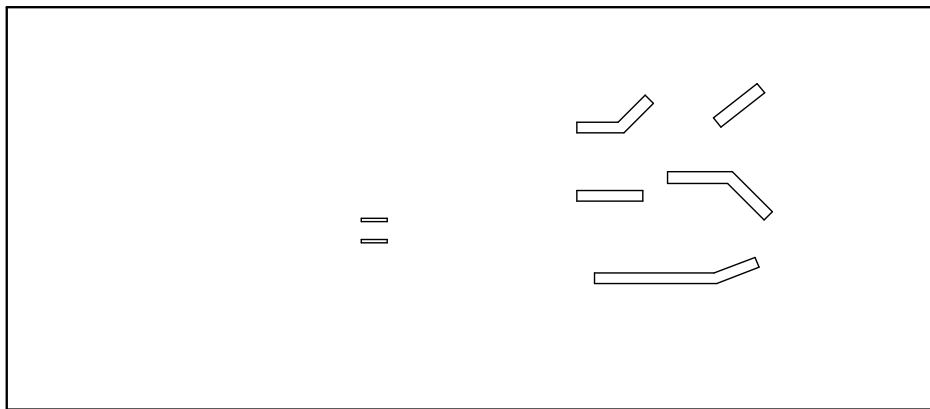


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40381		
PLOT NAME = Bottom Overlay	GENERATED : 4/3/2018	5:31:47 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	2	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	12	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	1	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◻	4	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
◻	4	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	4	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	12	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⌒	8	37.40mil (0.950mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
◇	3	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	10	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	9	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	76 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40381		
PLOT NAME = Drill Drawing	GENERATED : 4/3/2018	5:31:48 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40381	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40381		
PLOT NAME = Board Dimensions	GENERATED : 4/3/2018 5:31:49 PM	TEXAS INSTRUMENTS	



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